

# LNJ324C43RA

## Hight Bright Surface Mounting Chip LED

3528 (PLCC2) Type

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$ 

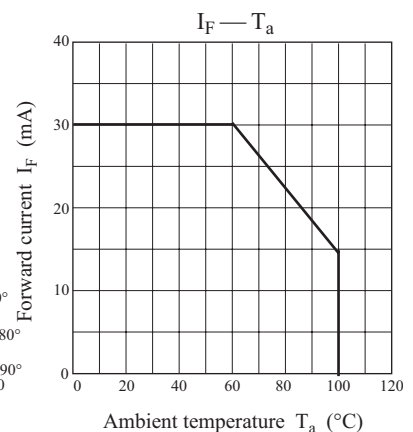
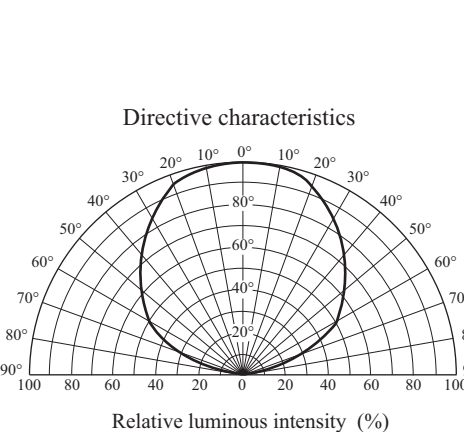
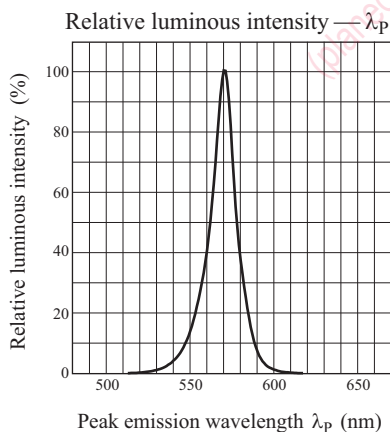
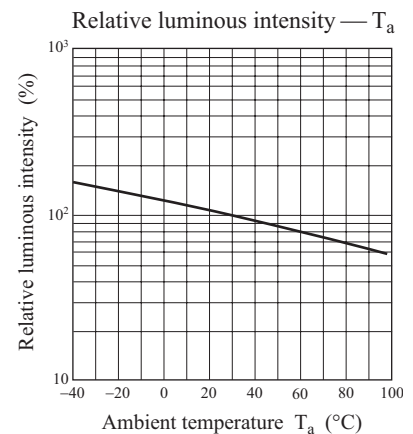
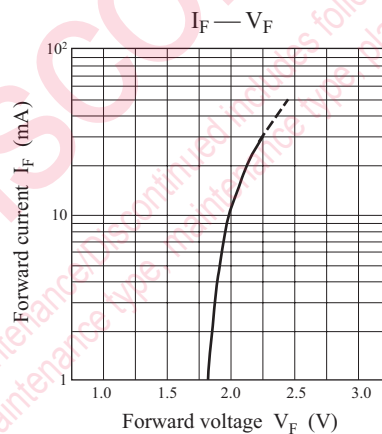
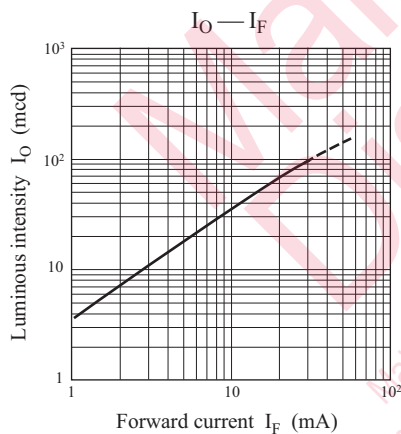
Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	80	mW
Forward current	$I_F$	30	mA
Pulse forward current *	$I_{FP}$	90	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-40 to +100	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.**■ Lighting Color**

- Yellow Green

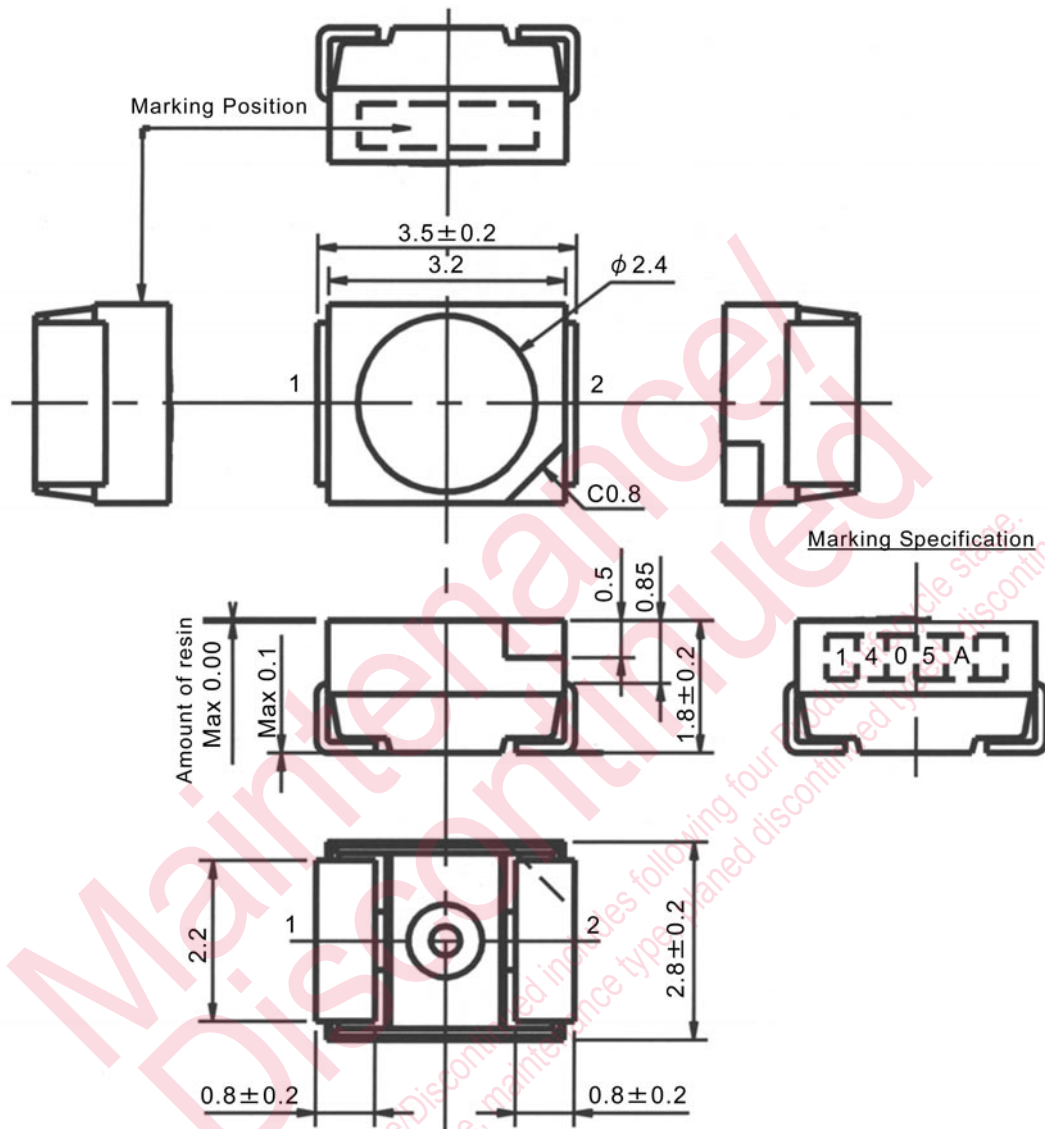
**■ Electro-Optical Characteristics**  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ 

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 20\text{ mA}$	40	70	130	mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 20\text{ mA}$		2.1	2.5	V
Peak emission wavelength	$\lambda_P$	$I_F = 20\text{ mA}$		571		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 20\text{ mA}$	565	572	577	nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		20		nm

Note) \*1: Measurement tolerance:  $\pm 15\%$ \*2: Measurement tolerance:  $\pm 2\text{ nm}$ 

■ Package (Unit: mm)

LLDFTR4J2400



- Pin name
- 1: Anode
- 2: Cathode

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